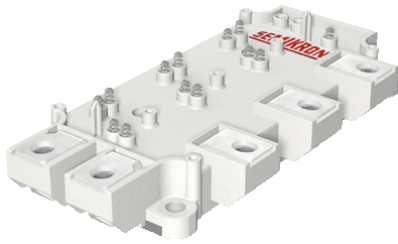


SEMiX251GD126HDs



SEMiX[®]13

Trench IGBT Modules

SEMiX251GD126HDs

Preliminary Data

Features

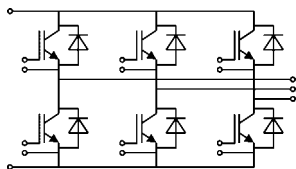
- Homogeneous Si
- Trench = Trenchgate technology
- $V_{CE(sat)}$ with positive temperature coefficient
- High short circuit capability
- UL recognised file no. E63532

Typical Applications

- AC inverter drives
- UPS
- Electronic Welding

Remarks

- Case temperatur limited to $T_C=125^\circ\text{C}$ max.
- Not for new design



GD

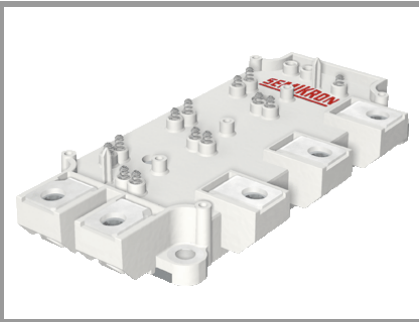
Absolute Maximum Ratings

Symbol	Conditions		Values	Unit
IGBT				
V _{CES}			1200	V
I _C	T _j = 150 °C	T _c = 25 °C	242	A
		T _c = 80 °C	170	A
I _{Cnom}			150	A
I _{CRM}	I _{CRM} = 2xI _{Cnom}		300	A
V _{GES}			-20 ... 20	V
t _{psc}	V _{CC} = 600 V V _{GE} ≤ 20 V T _j = 125 °C V _{CES} ≤ 1200 V		10	µs
T _j			-40 ... 150	°C
Inverse diode				
I _F	T _j = 150 °C	T _c = 25 °C	207	A
		T _c = 80 °C	143	A
I _{Fnom}			150	A
I _{FRM}	I _{FRM} = 2xI _{Fnom}		300	A
I _{FSM}	t _p = 10 ms, sin 180°, T _j = 25 °C		1000	A
T _j			-40 ... 150	°C
Module				
I _{t(RMS)}			600	A
T _{stg}			-40 ... 125	°C
V _{isol}	AC sinus 50Hz, t = 1 min		4000	V

Characteristics

Symbol	Conditions	min.	typ.	max.	Unit
IGBT					
$V_{CE(sat)}$	$I_C = 150\text{ A}$ $V_{GE} = 15\text{ V}$ chipelevel	$T_j = 25^\circ\text{C}$	1.7	2.1	V
		$T_j = 125^\circ\text{C}$	2.00	2.45	V
V_{CE0}		$T_j = 25^\circ\text{C}$	1	1.2	V
		$T_j = 125^\circ\text{C}$	0.9	1.1	V
r_{CE}	$V_{GE} = 15\text{ V}$	$T_j = 25^\circ\text{C}$	4.7	6.0	$\text{m}\Omega$
		$T_j = 125^\circ\text{C}$	7.3	9.0	$\text{m}\Omega$
$V_{GE(th)}$	$V_{GE}=V_{CE}, I_C = 6\text{ mA}$	5	5.8	6.5	V
I_{CES}	$V_{GE} = 0\text{ V}$ $V_{CE} = 1200\text{ V}$	$T_j = 25^\circ\text{C}$	0.1	0.3	mA
		$T_j = 125^\circ\text{C}$			mA
C_{ies}	$V_{CE} = 25\text{ V}$	$f = 1\text{ MHz}$	10.8		nF
C_{oes}	$V_{GE} = 0\text{ V}$	$f = 1\text{ MHz}$	0.56		nF
C_{res}		$f = 1\text{ MHz}$	0.49		nF
Q_G	$V_{GE} = -8\text{ V...} + 15\text{ V}$		1200		nC
R_{Gint}	$T_j = 25^\circ\text{C}$		5.00		Ω
$t_{d(on)}$	$V_{CC} = 600\text{ V}$		250		ns
t_r	$I_C = 150\text{ A}$		45		ns
E_{on}	$T_j = 125^\circ\text{C}$		19		mJ
$t_{d(off)}$	$R_{G on} = 1\text{ }\Omega$		525		ns
t_f	$R_{G off} = 1\text{ }\Omega$		100		ns
E_{off}			22		mJ
$R_{th(j-c)}$	per IGBT			0.15	K/W
$R_{th(j-s)}$	per IGBT				K/W

SEMiX251GD126HDs



SEMiX®13

Trench IGBT Modules

SEMiX251GD126HDs

Preliminary Data

Features

- Homogeneous Si
- Trench = Trenchgate technology
- $V_{CE(sat)}$ with positive temperature coefficient
- High short circuit capability
- UL recognised file no. E63532

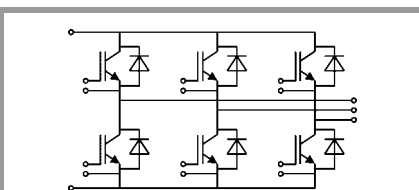
Typical Applications

- AC inverter drives
- UPS
- Electronic Welding

Remarks

- Case temperatur limited to $T_C=125^\circ\text{C}$ max.
- Not for new design

Characteristics						
Symbol	Conditions		min.	typ.	max.	Unit
Inverse diode						
V _F = V _{EC}	I _F = 150 A	T _j = 25 °C		1.6	1.8	V
	V _{GE} = 0 V chiplevel	T _j = 125 °C		1.6	1.8	V
V _{F0}		T _j = 25 °C	0.9	1	1.1	V
		T _j = 125 °C	0.7	0.8	0.9	V
r _F		T _j = 25 °C	3.3	4.0	4.7	mΩ
		T _j = 125 °C	4.7	5.3	6.0	mΩ
I _{RRM}	I _F = 150 A	T _j = 125 °C		190		A
Q _{rr}	di/dt _{off} = 3950 A/μs	T _j = 125 °C		35		μC
E _{rr}	V _{GE} = -15 V V _{CC} = 600 V	T _j = 125 °C		14.5		mJ
R _{th(j-c)}	per diode				0.28	K/W
R _{th(j-s)}	per diode					K/W
Module						
L _{CE}				20		nH
R _{CC'+EE'}	res., terminal-chip	T _C = 25 °C		0.7		mΩ
		T _C = 125 °C		1		mΩ
R _{th(c-s)}	per module			0.04		K/W
M _s	to heat sink (M5)		3		5	Nm
M _t		to terminals (M6)	2.5		5	Nm
						Nm
w					350	g
Temperature sensor						
R ₁₀₀	T _c =100°C (R ₂₅ =5 kΩ)			0,493 ±5%		kΩ
B _{100/125}	R _(T) =R ₁₀₀ exp[B _{100/125} (1/T-1/T ₁₀₀)]; T[K];			3550 ±2%		K



GD

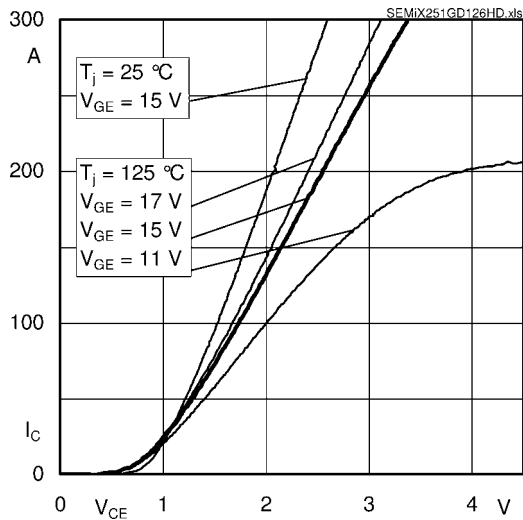


Fig. 1 Typ. output characteristic, inclusive $R_{CC'}+EE'$

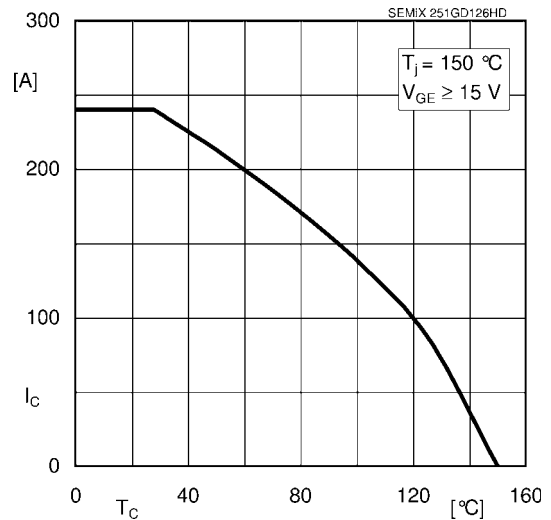


Fig. 2 Rated current vs. temperature $I_C = f(T_C)$

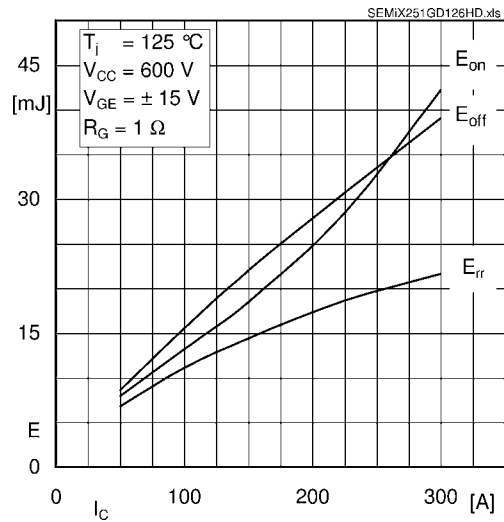


Fig. 3 Typ. turn-on /-off energy = $f(I_C)$

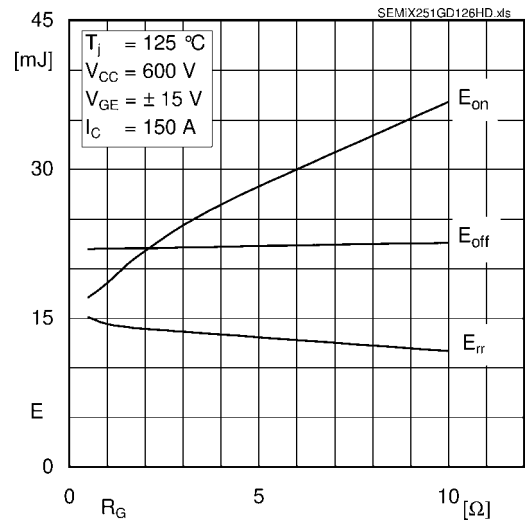


Fig. 4 Typ. turn-on /-off energy = $f(R_G)$

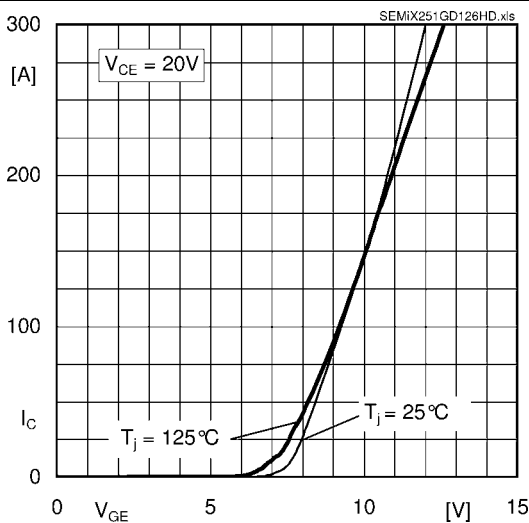


Fig. 5 Typ. transfer characteristic

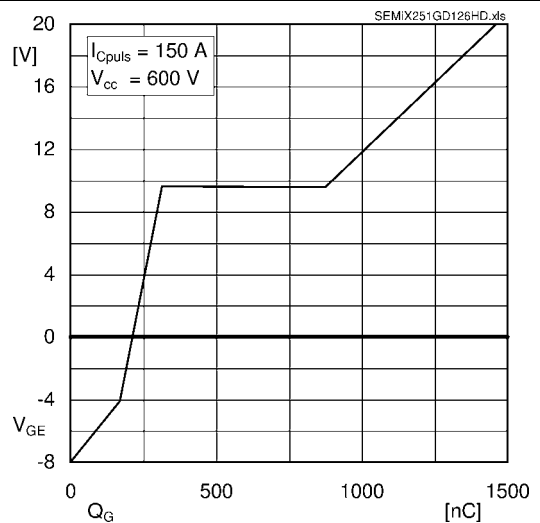


Fig. 6 Typ. gate charge characteristic

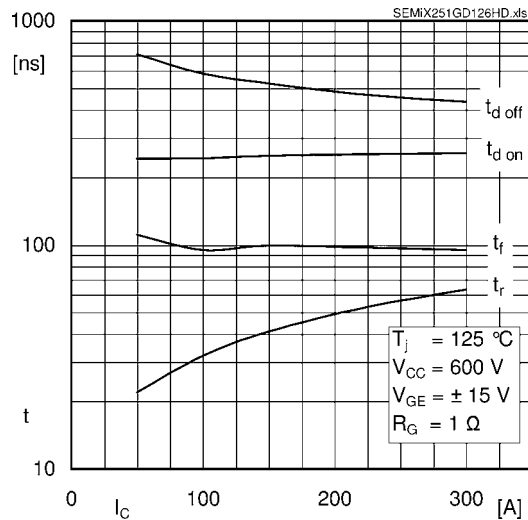


Fig. 7 Typ. switching times vs. I_C

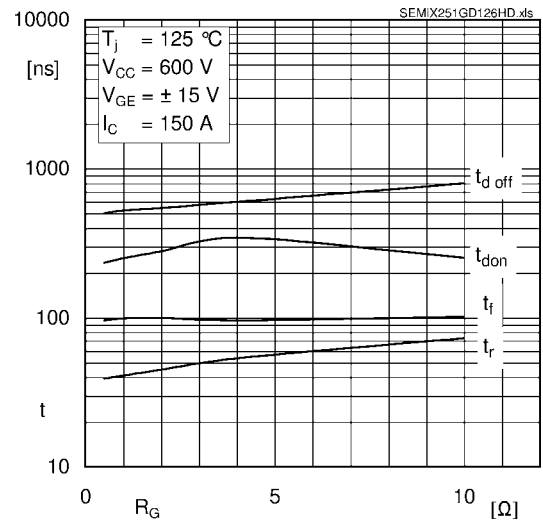


Fig. 8 Typ. switching times vs. gate resistor R_G

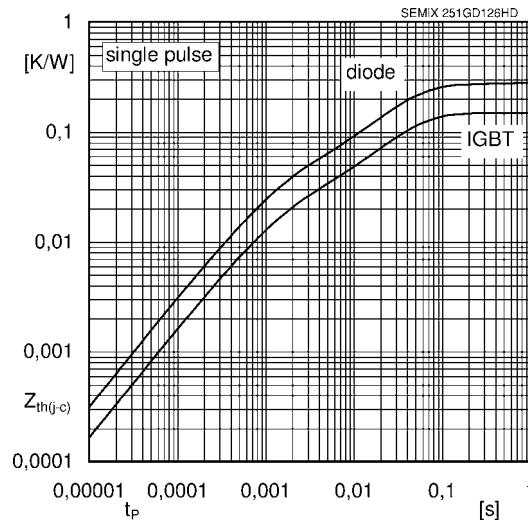


Fig. 9 Typ. transient thermal impedance

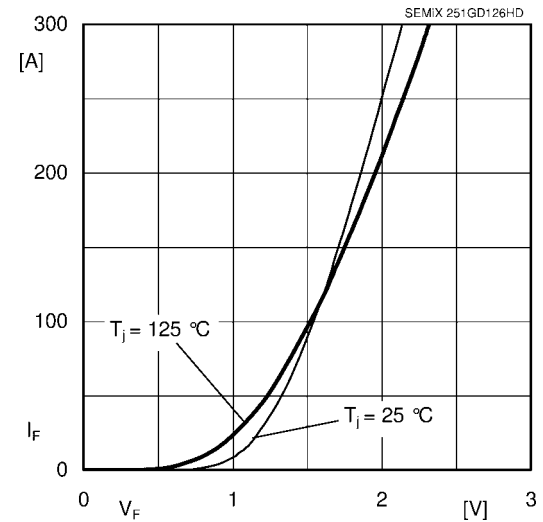


Fig. 10 Typ. CAL diode forward charact., incl. $R_{CC'+EE'}$

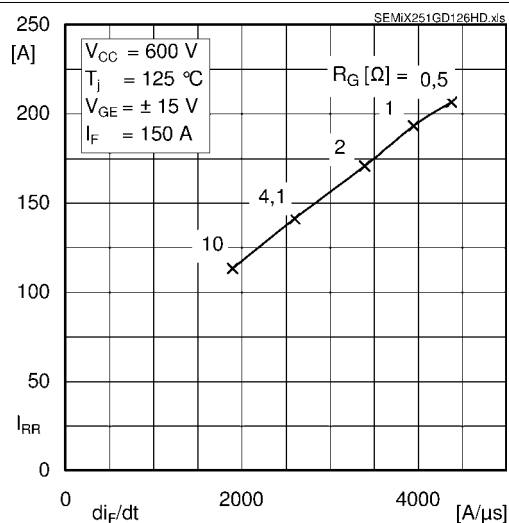


Fig. 11 Typ. CAL diode peak reverse recovery current

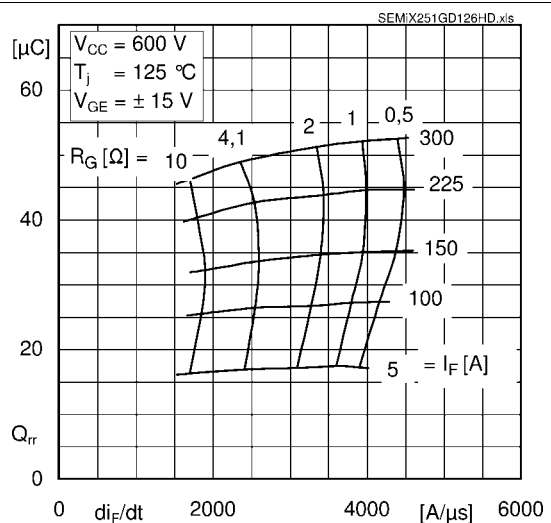
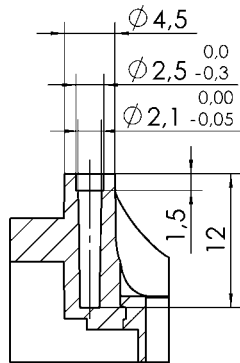


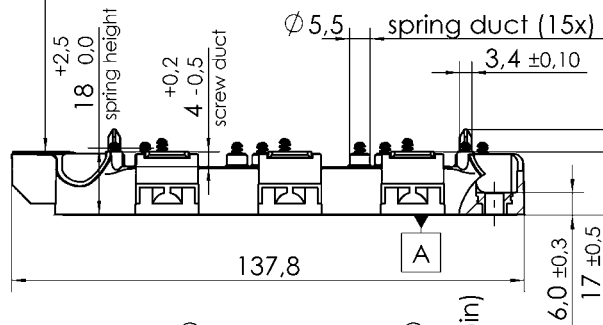
Fig. 12 Typ. CAL diode recovery charge

case: SEMiX 13

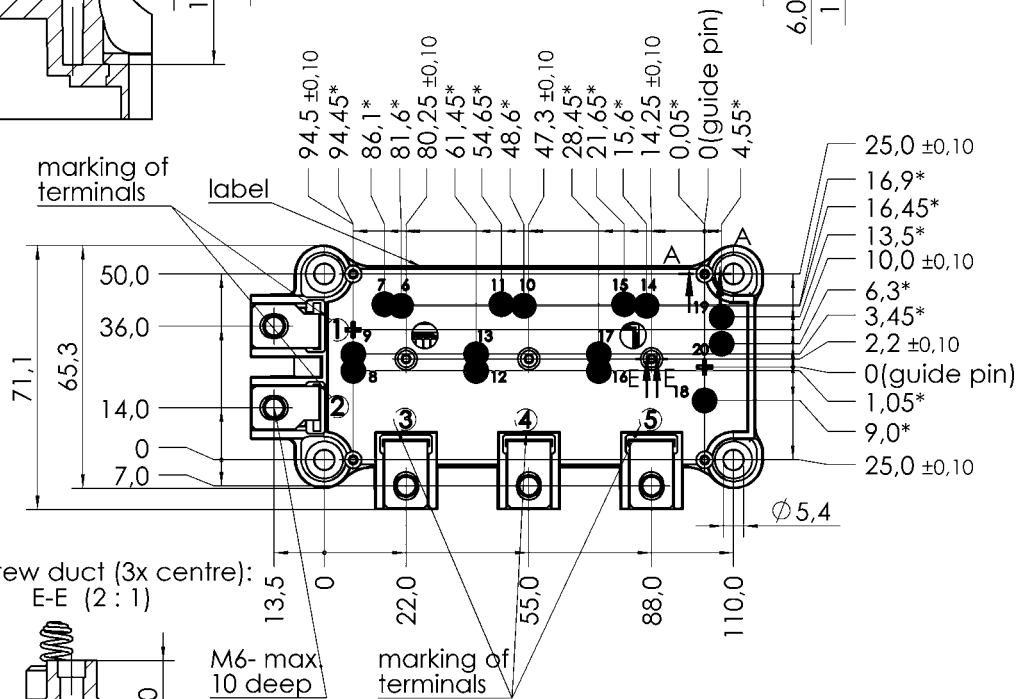
screw duct (4x):
A-A (2:1)



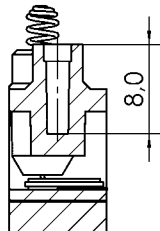
$\square$	0,3	main terminal +, - / ~, ~
$\parallel$	0,2	A



All measures in Z-direction
valid as mounted to heat sink



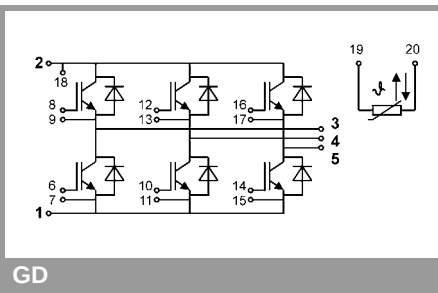
screw duct (3x centre):
E-E (2:1)



* all measures with $\pm 0,2$

Rules for the contact PCB:
- spring landing pad = $\phi 3,5 \pm 0,2$
- holes guidepins = $\phi 4 \pm 0,1$

SEMiX 13



GD

This is an electrostatic discharge sensitive device (ESDS), international standard IEC 60747-1, Chapter IX

This technical information specifies semiconductor devices but promises no characteristics. No warranty or guarantee expressed or implied is made regarding delivery, performance or suitability.